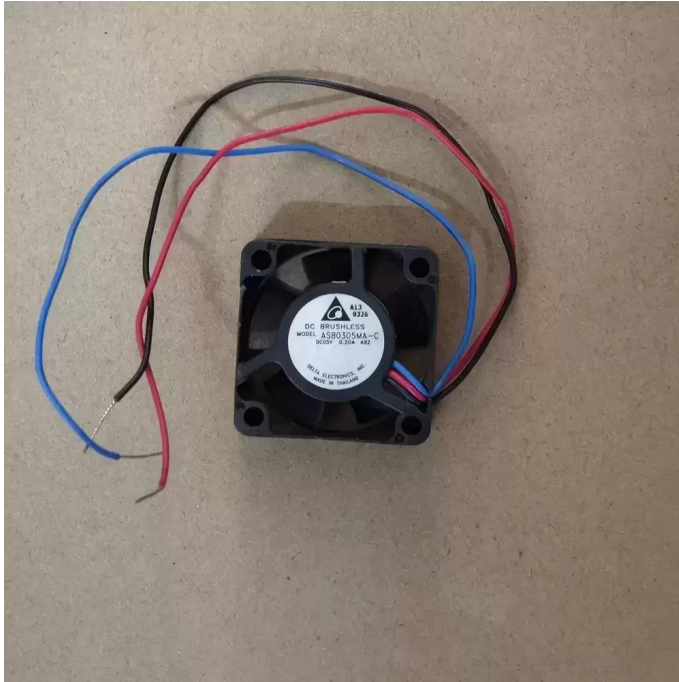


ASB0305MA-CA8Z Delta 5VDC 30x30x10mm DC Brushless Fan Datasheet



Brand: Delta

SKU: [1029544724152](#)

Category: Axial & Centrifugal Fans

Price: **\$19.99**

E-mail: sales@equipspares.com

Web: <https://www.equipspares.com>

Product Page:

<https://www.equipspares.com/product/asb0305ma-ca8z-delta-5vdc-30x30x10mm-dc-brushless-fan>

Product Description

Delta ASB0305MA-CA8Z is a compact 30 x 30 x 10 mm brushless axial fan operating at a nominal 5 VDC with a rated current of 0.20 A and power consumption of 1.0 W. This tubeaxial cooling component features a high-reliability sleeve bearing system and a 3-wire interface providing a tachometer signal for precise rotational speed monitoring. The structural frame and impeller are constructed from UL 94V-0 rated thermoplastic, ensuring flame retardancy and structural integrity during continuous operation. It delivers an airflow of 3.4 CFM (0.095 m³/min) and a static pressure of 0.110 in H₂O while maintaining a low acoustic profile of 21.0 dB-A.

ASB0305MA-CA8Z Specifications

Model Number: ASB0305MA-CA8Z

Brand: Delta Electronics

Category: DC Brushless Axial Fan

Dimensions: 30 x 30 x 10 mm

Rated Voltage: 5 VDC

Operating Voltage Range: 4.5 to 5.5 VDC

Rated Current: 0.11 A (0.20 A Max)

Rated Input Power: 0.55 W (1.0 W Max)

Rated Speed: 8000 RPM

Maximum Air Flow: 3.40 CFM (0.095 m³/min)

Maximum Static Pressure: 0.110 in H₂O (2.80 mm H₂O)

Noise Level: 21.0 dB-A

Bearing Type: Sleeve Bearing

Interface: 3-wire (Red: Positive, Black: Negative, Blue: Tachometer/Sensor)

Lead Wire Length: 270 mm

Material Frame: Plastic (UL 94V-0)

Material Impeller: Plastic (UL 94V-0)

Operating Temperature: -10 to 70 °C

Storage Temperature: -40 to 75 °C

Weight: 10.5 g

Safety Approvals: UL, CUR, TUV, CE

Features: Locked Rotor Sensor, Speed Sensor (Tach), Auto Restart

ASB0305MA-CA8Z Applications

Primary applications include integration into laptop internal cooling assemblies, compact network switch enclosures, and portable medical diagnostic equipment. Deployed within telecommunications base station modules, set-top boxes, and high-density power supply units to provide localized thermal management for sensitive microprocessors and power semiconductors.

Supplemental Images

